MDSA Series

SMD Low Profile High Current Molded Inductor

Size 7050



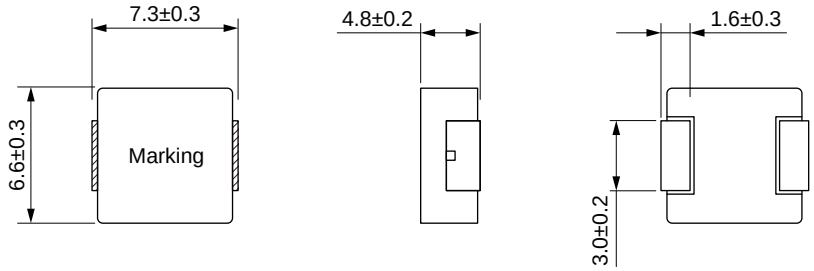
FEATURES

- Shielded construc on
- Capable of corresponding high frequency .
- Low loss realized with low DCR.
- High performance (Isat) realized by metal dust core.
- Ultra low buzz noise, due to composite construc on.
- 100% Lead(Pb)-Free and RoHS compliant.
- AEC-Q200 qualified
- Opera ng temperature: -55 to +155 °C (including self-temperature rise)
- Quan ty: 800PCS

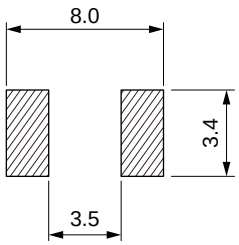
APPLICATION

- Noise filter for various drive circuitry requiring high temp. opera on and peak current handing capability.
- Boost-Converter
- Buck-Converter DC/DC

Dimensions: [mm]



Land Pattern: [mm]

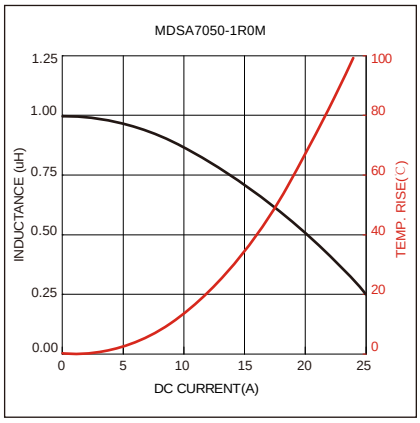


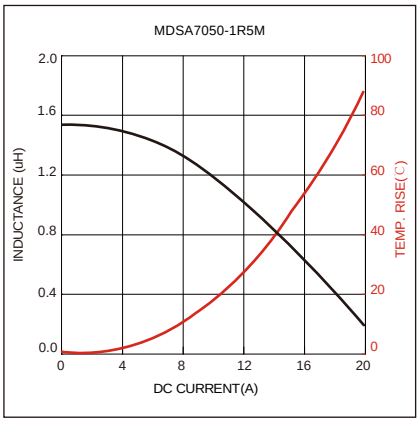
Electrical Properties:

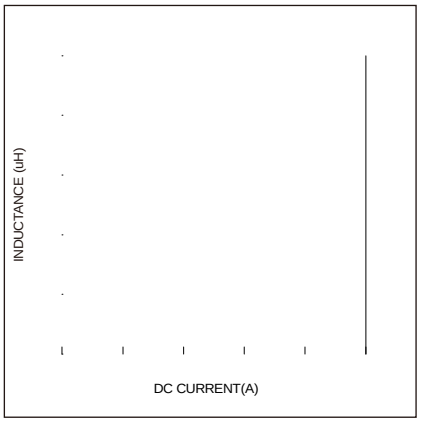
MDSA7050-1R0M	1.00	±20%	17.0	14.4	16.0	12.5	5.70	6.30
MDSA7050-1R5M	1.50	±20%	15.0	12.5	13.0	10.1	6.70	7.40
MDSA7050-2R2M	2.20	±20%	14.0	11.6	10.0	8.20	10.1	11.7
MDSA7050-3R3M	3.30	±20%	13.0	10.6	9.50	7.70	14.2	16.4
MDSA7050-4R7M	4.70	±20%	11.0	9.20	8.80	7.20	21.1	24.3
MDSA7050-5R6M	5.60	±20%	10.0	8.20	8.00	6.90	28.3	33.4
MDSA7050-6R8M	6.80	±20%	9.00	7.70	7.60	6.70	30.3	36.4
MDSA7050-8R2M	8.20	±20%	7.50	6.30	6.50	5.80	38.9	45.5

Saturation Current will cause L to drop approximately 30%
Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40°C

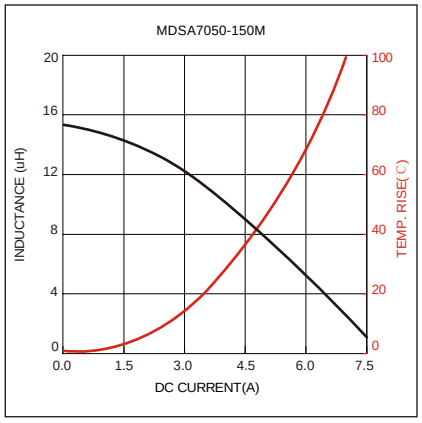
Typical Electrical Characteristics:

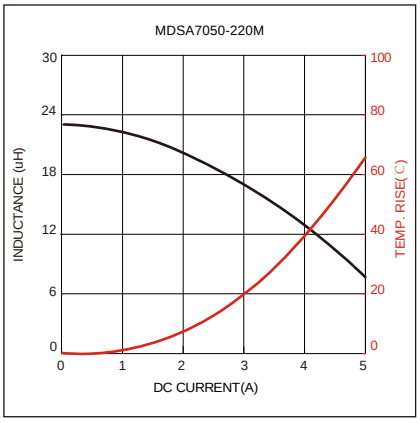


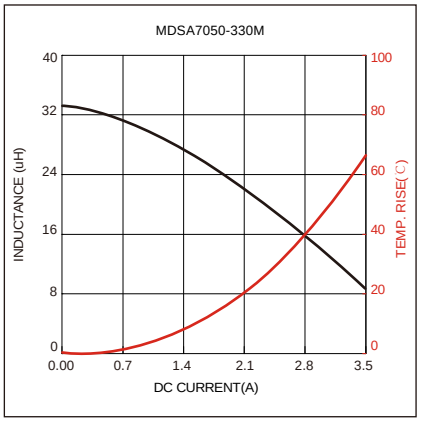


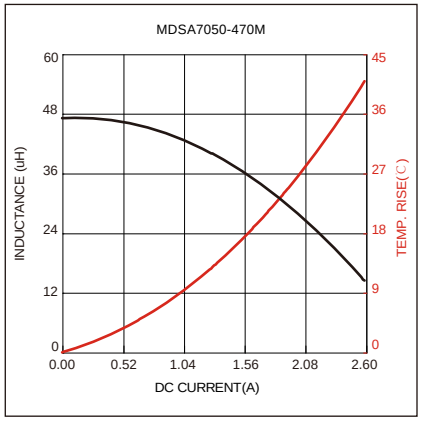


Typical Electrical Characteristics:









KOHER Electronics
F9, No. 4188, Huaning Rd, Minhang District, Shanghai
021-3470 sh EX5 1Re2group.com

Soldering Reflow:

Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

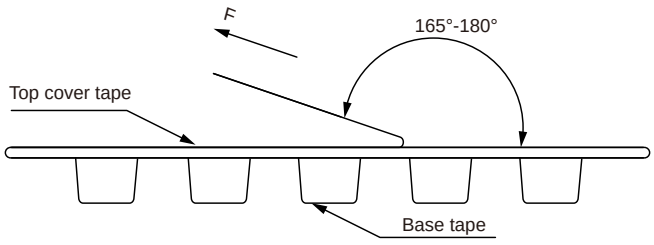
Max temperature: 260℃.

Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension:

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking

Reel Dimension：[mm]



Packaging Quantity: